

## IN THE CLAIMS

1. (Currently Amended) An assembly for providing solderless electrical connection between first and second substrates aligned in a stacked configuration, said assembly comprising:

a conductor assembly having at least one elongate conductor adapted to engage a first electrical contact on said first substrate on one end and a second electrical contact on said second substrate on a second end thereof, said at least one elongate conductor having three bends which create a ~~a three-bend~~ hook shape at both the first and second ends thereof to provide a spring force on both the first and second ends thereof and

means for retaining said at least one elongate conductor in abutting contact with said first and second contacts and thereby effect a solderless electrical connection between said first contact on said first substrate and said second contact on said second substrate.

2. Canceled

3. Canceled

4. (Currently Amended) The assembly of Claim 1 wherein said at least one elongate conductor is constrained by a dielectric between the ends thereof.

5. (Previously presented) The assembly of Claim 4 wherein said conductor assembly includes a plurality of conductors.

6. (Previously presented) The assembly of Claim 5 wherein said conductor assembly is retained within an elongate housing.

7. (Previously presented) The assembly of Claim 6 wherein said housing is retained within a frame.

8. (Previously presented) The assembly of Claim 7 wherein said housing is retained within said frame by at least one pin at each end thereof.

9. (Currently Amended) The assembly of Claim 8 wherein said pin is retained by said frame.

10. (Previously presented) A high density electrical assembly adapted to make solderless electrical contacts between plural circuit boards aligned in a stacked configuration, said assembly comprising:

a conductor assembly having plural elongate conductors adapted to engage a first electrical contact on a first circuit board on one end and a second electrical contact on a second circuit board on a second end thereof, each conductor having a three-bend hook shape at both the first and second ends thereof to provide a spring force on both the first and second ends thereof and constrained by a dielectric between the ends thereof and

means for retaining each conductor in abutting contact with said first and second contacts and thereby effect a solderless electrical connection between said first contact on said first substrate and said second contact on said second substrate.

11. (Canceled)